

Method for Producing a Protective Cover for a Device**ABSTRACT**

5

In a method for producing a protective cover for a device which is formed in a substrate, a first cover layer is initially deposited on the substrate, the first cover layer covering an area of the substrate which includes the device. Subsequently, an opening is formed in the first cover layer, the opening exposing that area of the substrate which includes the device. Then the opening formed in the first cover layer is filled up using a filling material. Subsequently, a second cover layer is deposited on the first cover layer and in the opening of the first cover layer which is filled up with the filling material. Thereafter, an opening is formed in the second cover layer to expose an area of the filling material. Finally, the filling material covering that area of the substrate which includes the device is removed, and the opening formed in the second cover layer is closed.

Fig. 1E

25